

SS-060-033-500PB-S2 500PB-S2



Description

Technical Data

Strain gauge

Type	HL-DMS
Number of grids	1
Grid width	0.15 mm
maximum width	3.3 mm
Grid length	0.84 mm
maximum length	7.62 mm
Resistance	500 Ohm
Tolerance resistance	10 %
Grid disposition	
Connection	Solder pad
Type	Semiconductor
Substrate	phenolic resin